



# STW60N65M5 STFW60N65M5

N-channel 650 V, 0.049  $\Omega$ , 46 A MDmesh™ V Power MOSFET  
in TO-247, TO-3PF

## Features

Order codes	V <sub>DSS</sub> @ T <sub>Jmax</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STFW60N65M5 STW60N65M5	710 V	< 0.059 $\Omega$	46 A

- Worldwide best R<sub>DS(on)</sub> \* area amongst the silicon based devices
- Higher V<sub>DSS</sub> rating
- High dv/dt capability
- Excellent switching performance
- Easy to drive
- 100% avalanche tested

## Application

Switching applications

## Description

The devices are N-channel MDmesh™ V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low on-resistance, which is unmatched among silicon-based Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

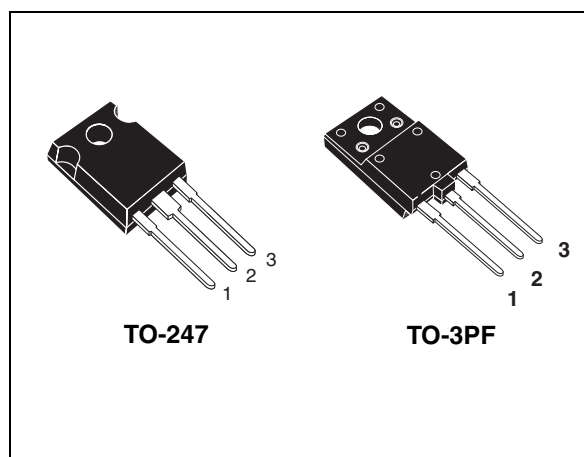


Figure 1. Internal schematic diagram

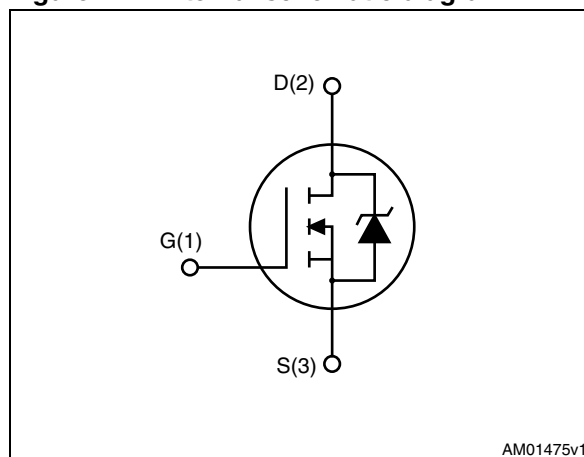


Table 1. Device summary

Order codes	Marking	Package	Packaging
STFW60N65M5 STW60N65M5	60N65M5	TO-3PF TO-247	Tube

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-247	TO-3PF	
$V_{GS}$	Gate-source voltage	± 25		V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	46		A
$I_D$	Drain current (continuous) at $T_C = 100\text{ °C}$	29		A
$I_{DM}^{(1)}$	Drain current (pulsed)	184		A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ °C}$	255	79	W
$I_{AR}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_j$ max)	12		A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ °C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	1400		mJ
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15		V/ns
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t=1\text{ s}$ ; $T_c=25\text{ °C}$ )		3500	V
$T_{stg}$	Storage temperature	- 55 to 150		°C
$T_j$	Max. operating junction temperature	150		°C

1. Pulse width limited by safe operating area

2.  $I_{SD} \leq 46\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ,  $V_{DD} = 400\text{ V}$ ,  $V_{Peak} < V_{(BR)DSS}$

**Table 3. Thermal data**

Symbol	Parameter	Value		Unit
		TO-247	TO-3PF	
$R_{thj-case}$	Thermal resistance junction-case max	0.49	1.58	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient max	50		°C/W
$T_l$	Maximum lead temperature for soldering purpose	300		°C

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0$	650			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ , $T_C = 125\text{ °C}$			1 100	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 25\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 23\text{ A}$		0.049	0.059	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$	-	6810	-	pF
$C_{oss}$	Output capacitance			141		pF
$C_{rss}$	Reverse transfer capacitance			6.2		pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }520\text{ V}$ , $V_{GS} = 0$	-	480	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related			140		pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	1	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 520\text{ V}$ , $I_D = 23\text{ A}$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 17</a> )	-	139	-	nC
$Q_{gs}$	Gate-source charge			34		nC
$Q_{gd}$	Gate-drain charge			52		nC

- $C_{o(tr)}^{(1)}$  is a constant capacitance value that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .
- $C_{o(er)}^{(2)}$  is a constant capacitance value that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_d$ (v)	Voltage delay time	$V_{DD} = 400\text{ V}$ , $I_D = 30\text{ A}$ ,		90		ns
$t_r$ (v)	Voltage rise time	$R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$		11		ns
$t_f$ (i)	Current fall time	(see <a href="#">Figure 18</a> )	-	13	-	ns
$t_c$ (off)	Crossing time	(see <a href="#">Figure 21</a> )		16		ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current				46	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		184	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 46\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 46\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		448		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100\text{ V}$ (see <a href="#">Figure 21</a> )	-	10		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			45		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 46\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		534		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$	-	14		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see <a href="#">Figure 21</a> )		52		A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-3FP

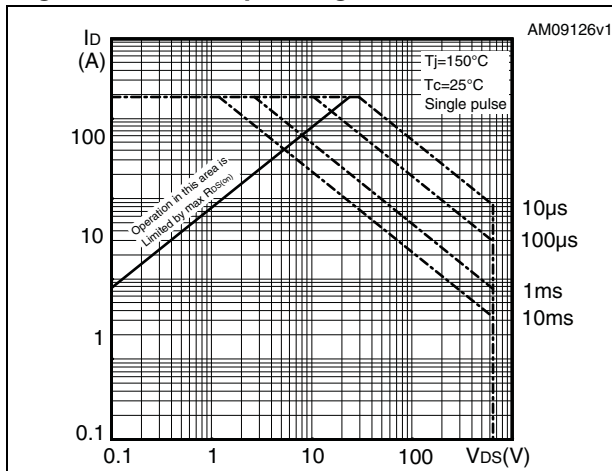


Figure 3. Thermal impedance for TO-3FP

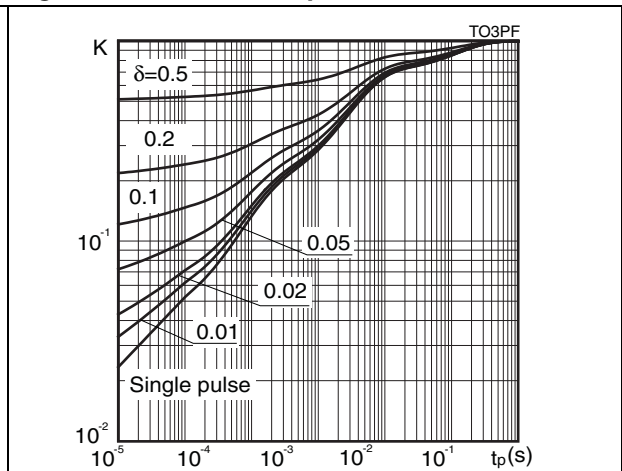


Figure 4. Safe operating area for TO-247

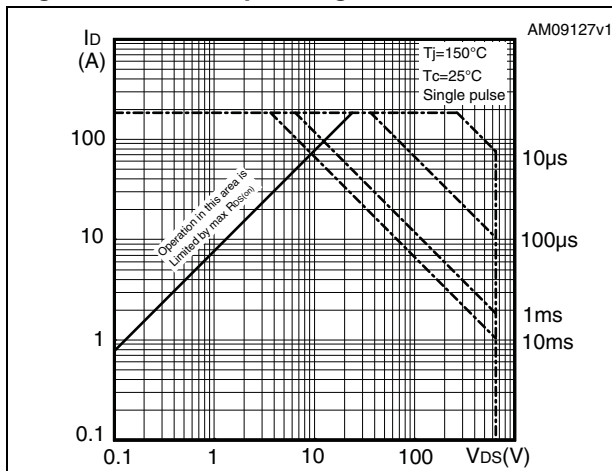


Figure 5. Thermal impedance for TO-247

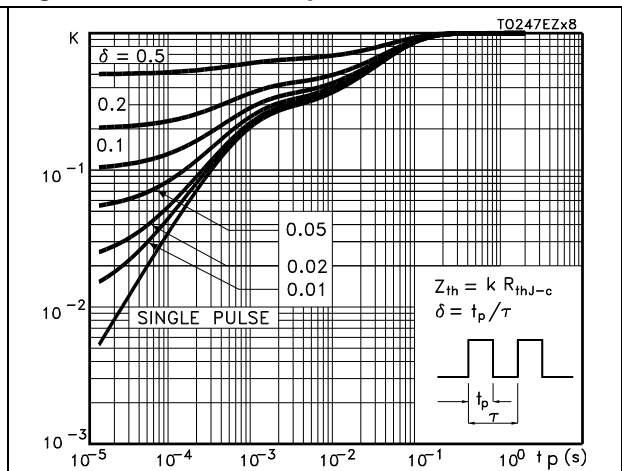


Figure 6. Output characteristics

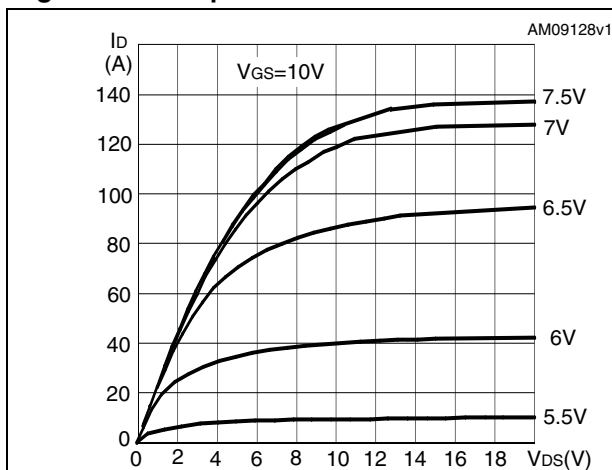


Figure 7. Transfer characteristics

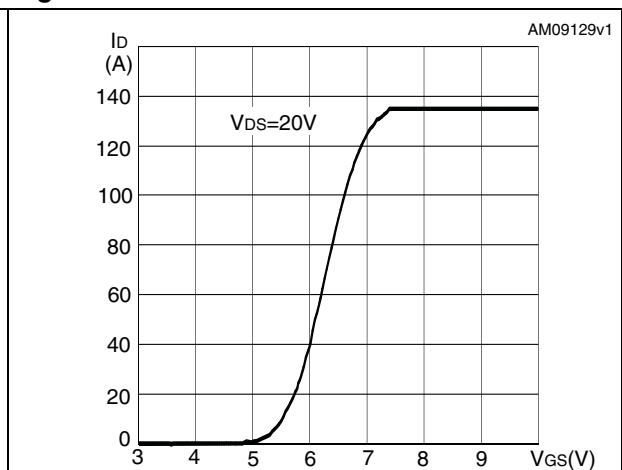


Figure 8. Gate charge vs gate-source voltage Figure 9. Static drain-source on resistance

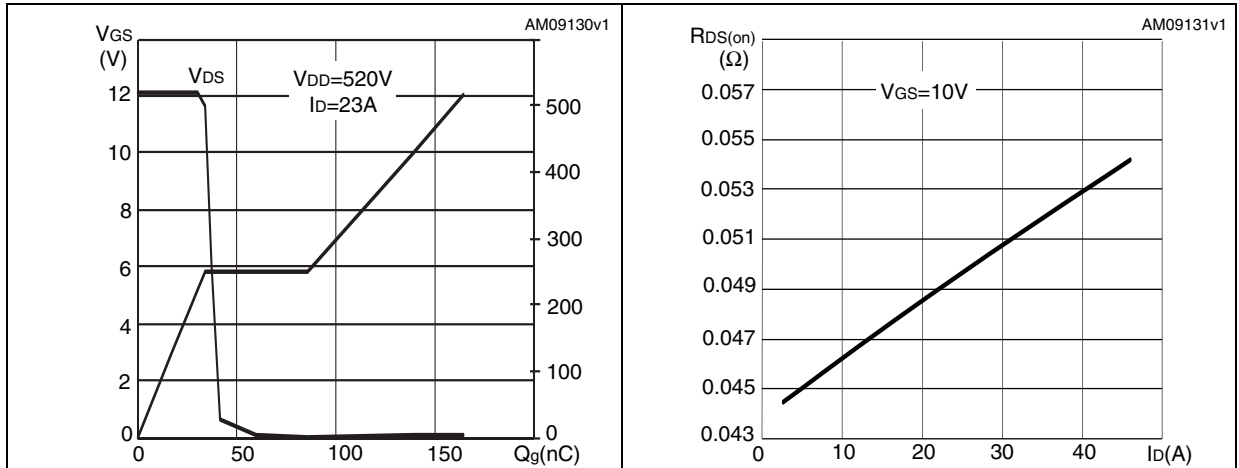


Figure 10. Capacitance variations Figure 11. Output capacitance stored energy

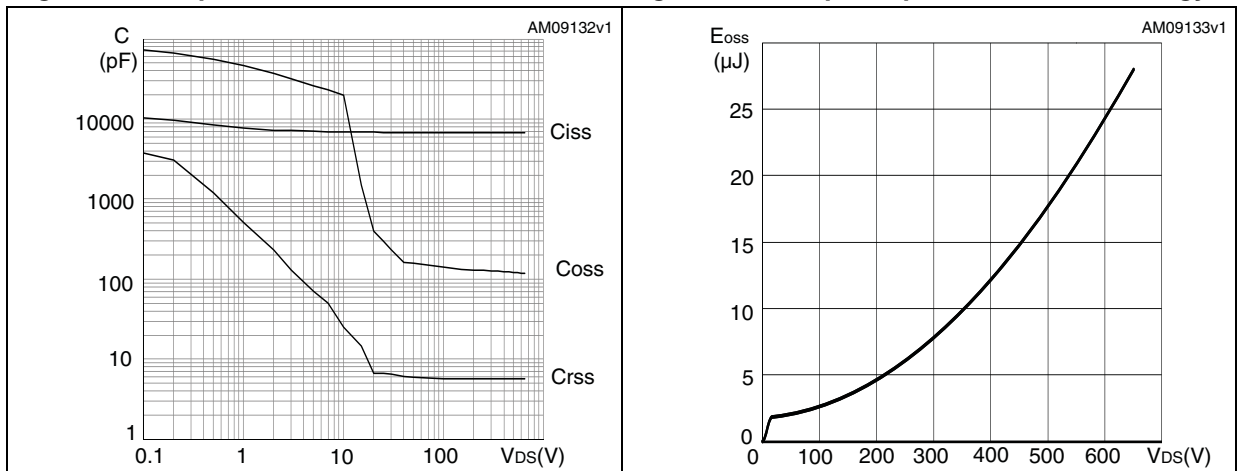


Figure 12. Normalized gate threshold voltage vs temperature Figure 13. Normalized on resistance vs temperature

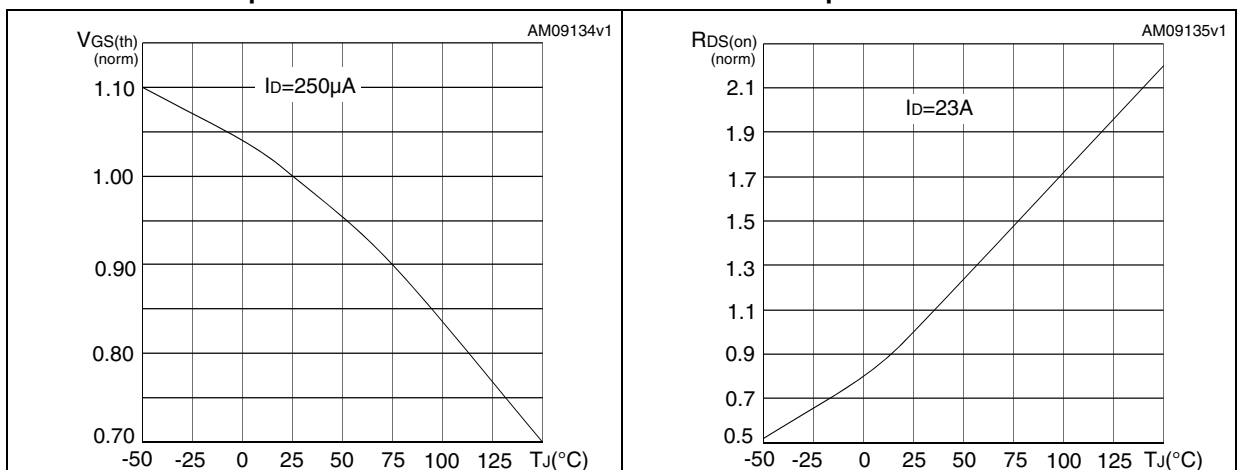
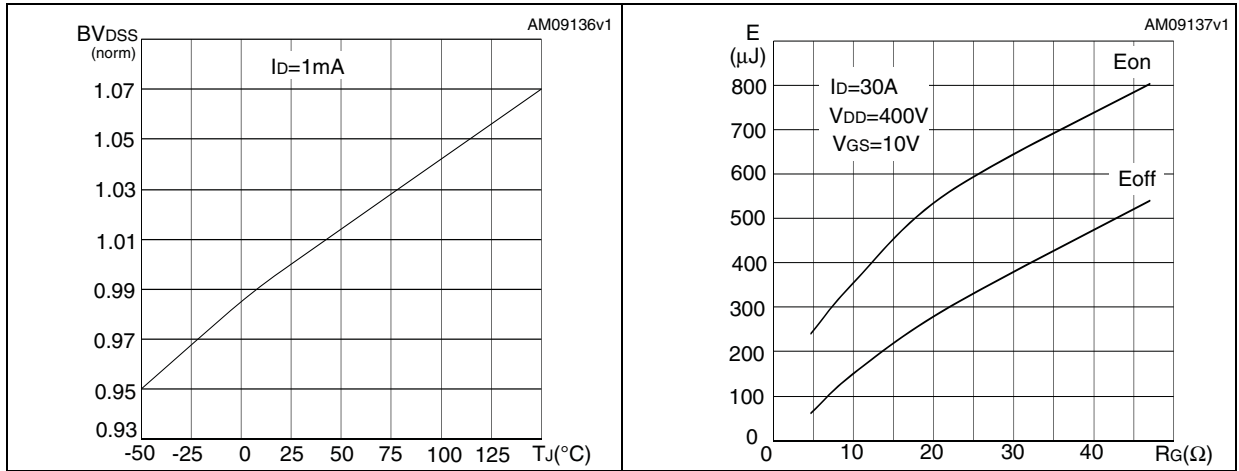


Figure 14. Normalized  $B_{VDSS}$  vs temperature

Figure 15. Switching losses vs gate resistance (1)

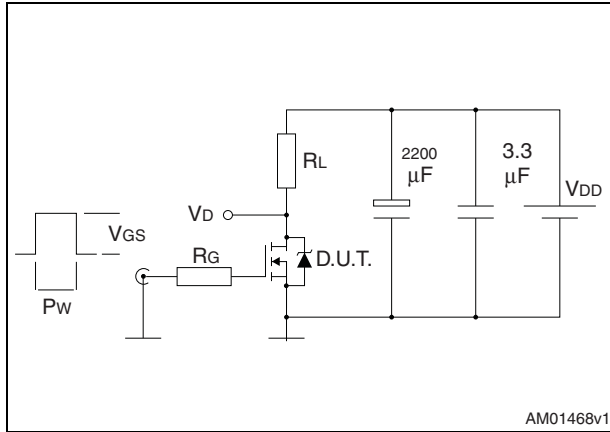


1.  $E_{on}$  including reverse recovery of a SiC diode



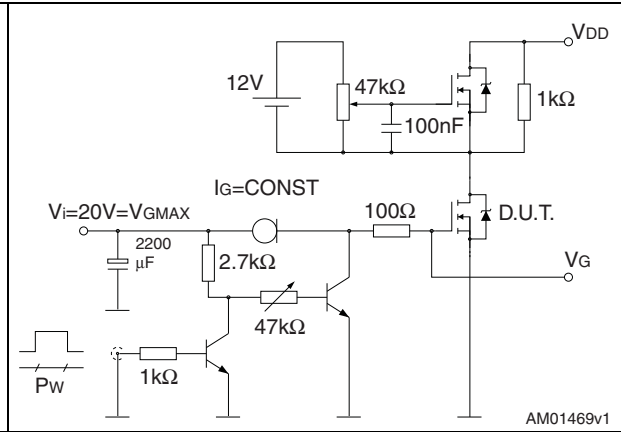
### 3 Test circuits

**Figure 16. Switching times test circuit for resistive load**



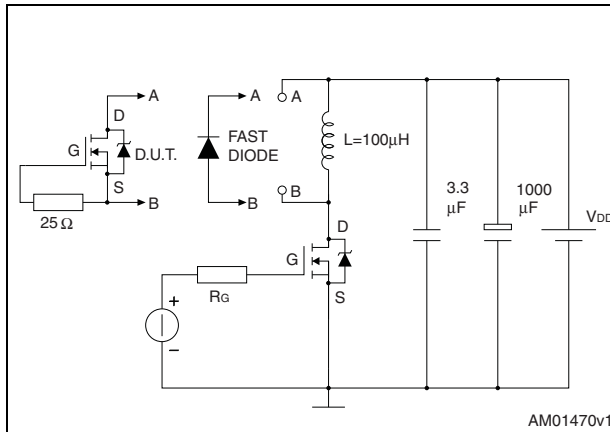
AM01468v1

**Figure 17. Gate charge test circuit**



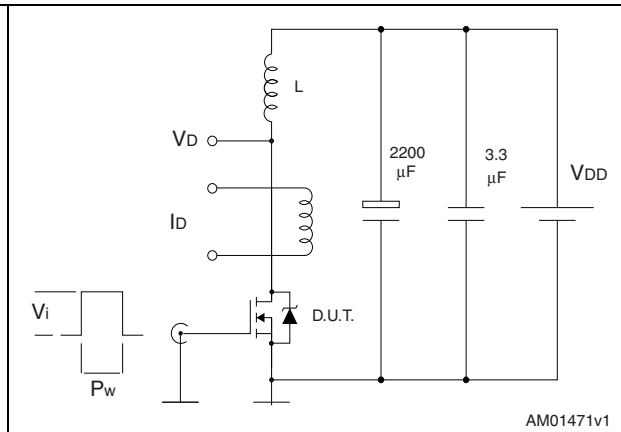
AM01469v1

**Figure 18. Test circuit for inductive load switching and diode recovery times**



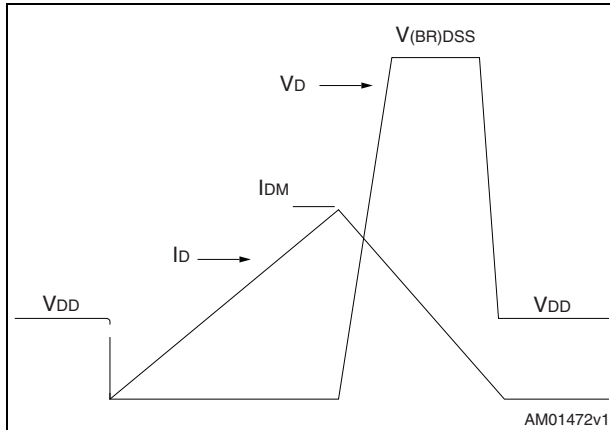
AM01470v1

**Figure 19. Unclamped inductive load test circuit**



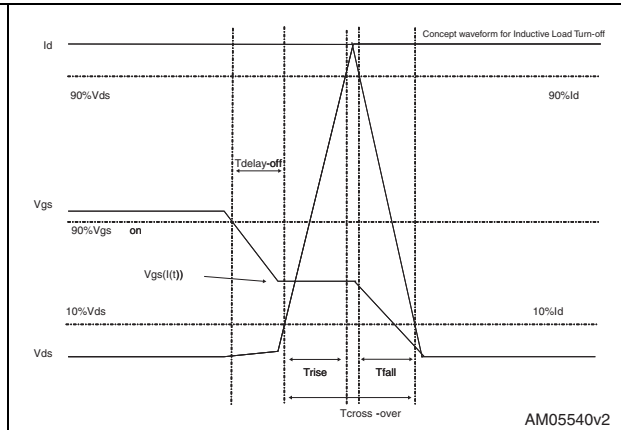
AM01471v1

**Figure 20. Unclamped inductive waveform**



AM01472v1

**Figure 21. Switching time waveform**



AM05540v2

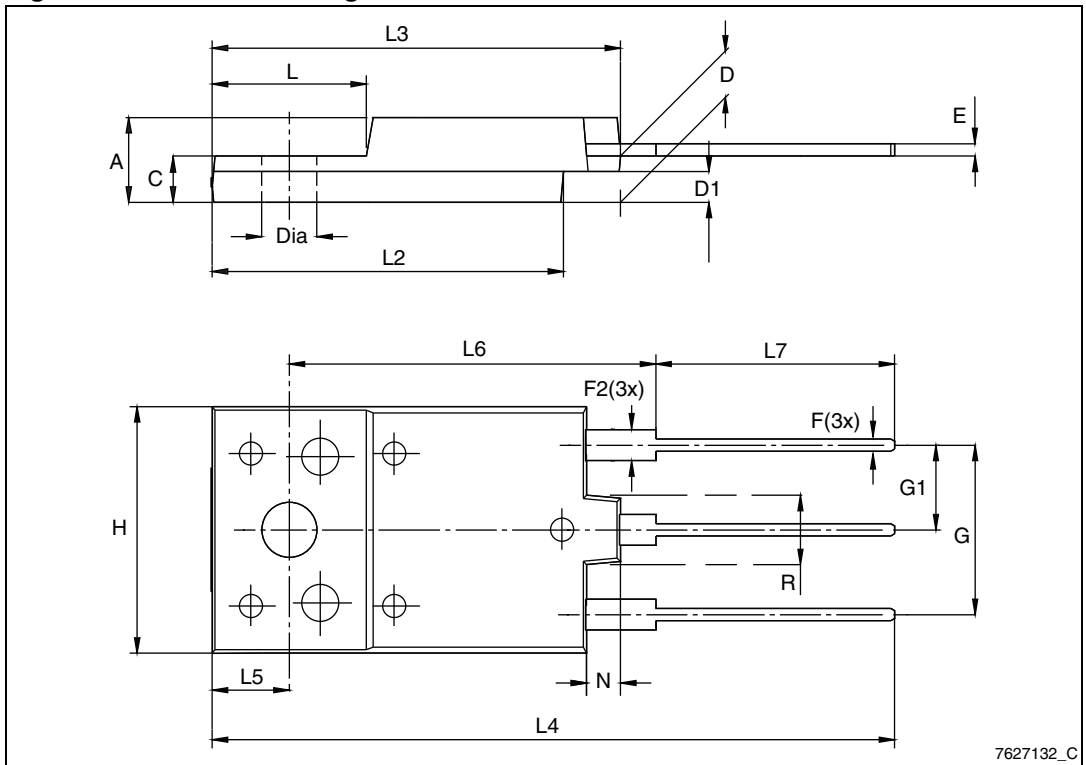
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

Table 8. TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

Figure 22. TO-3PF drawing

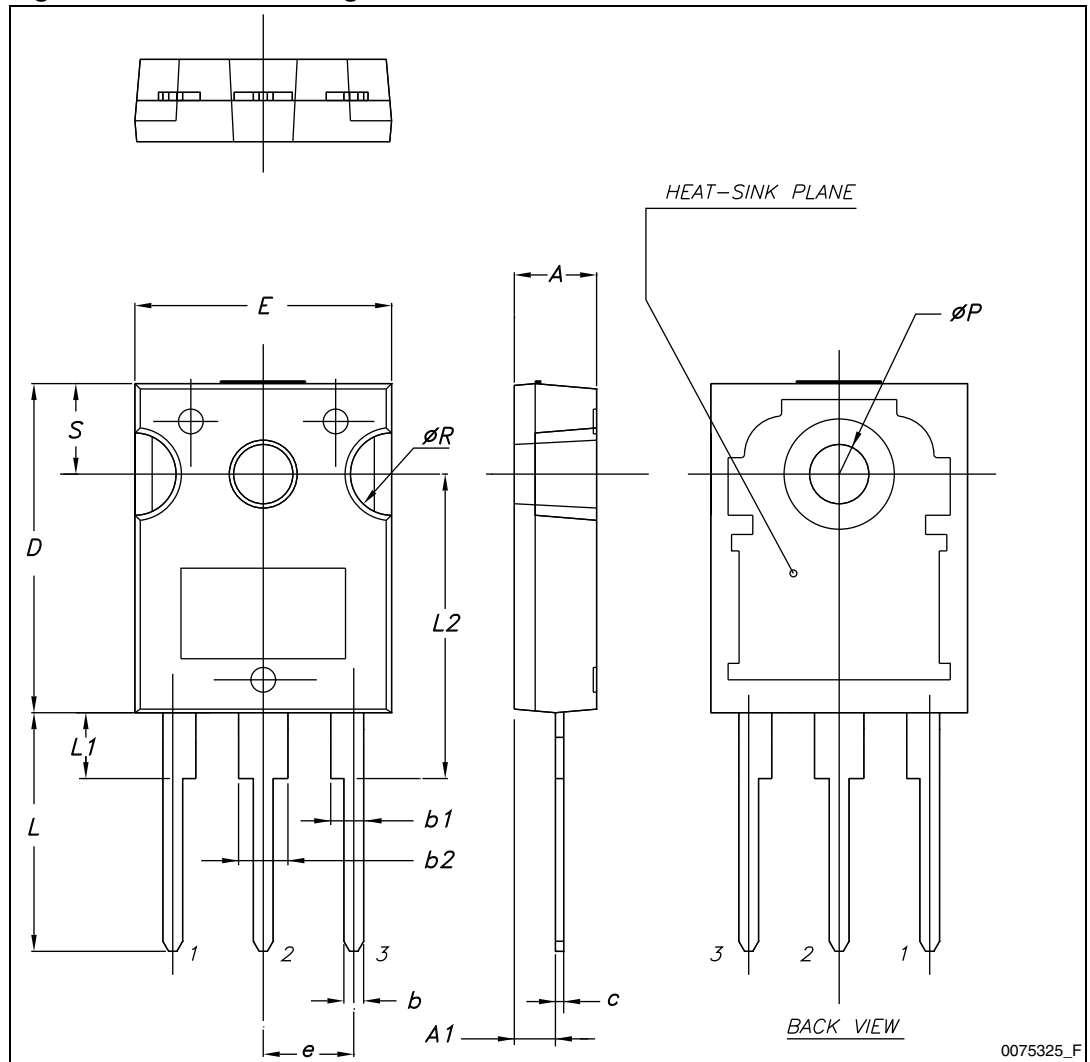


7627132\_C

Table 9. TO-247 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e		5.45	
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S		5.50	

Figure 23. TO-247 drawing



## 5 Revision history

Table 10. Document revision history

Date	Revision	Changes
15-Nov-2010	1	First release.
05-May-2011	2	Document status promoted from preliminary data to datasheet.

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